

CLAIMS

1. A cover plate for covering an opening of a casing in which a solid state imaging device is disposed, said cover plate comprising:

5 a transparent cover plate member that hermetically covers said opening; and

a conductive film layer that covers an outermost surface of said transparent cover plate member.

2. A cover plate according to claim 1, wherein said conductive film layer comprises a metallic film layer.

3. A cover plate according to claim 2, wherein said metallic film layer comprises a Cr film layer.

4. A cover plate according to claim 1, wherein said transparent cover plate member comprises a plurality of laminated transparent plates and at least one of said transparent plates comprises an optical low-pass filter.

5. A cover plate according to claim 4, wherein said optical low-pass filter comprises a plurality of lithium niobate plates.

6. A cover plate according to claim 1, wherein said transparent cover plate member comprises a plurality of laminated transparent plates and at least one of said transparent plates comprises an infrared cut-off filter.

7. A cover plate according to claim 6, wherein at least one of said transparent plates comprises an optical

low-pass filter.

5 8. A cover plate according to claim 7, wherein said infrared cut-off filter and said optical low-pass filter are arranged so that said infrared cut-off filter is disposed at a side closer to said solid state imaging device.

9. A cover plate according to claim 1, wherein said transparent cover plate member comprises a plurality of laminated transparent plates and at least one of said transparent plates comprises a cover glass.

10. A cover plate according to claim 1, wherein said transparent cover plate member comprises at least one lithium niobate plate and said conductive film layer is formed on at least one side of said lithium niobate plate.

11. A cover plate according to claim 1, wherein said transparent cover plate member comprises at least one infrared cut-off filter and said conductive film layer is formed on at least one side of said infrared cut-off filter.

12. A cover plate according to claim 1, wherein said transparent cover plate member comprises at least one cover glass and said conductive film layer is formed on at least one side of said cover glass.

13. An image pickup device, comprising:

a solid state imaging device;

a casing to which said state imaging device is

disposed;

a transparent cover plate member that hermetically covers an opening of said casing; and

a conductive film layer that covers an outermost surface of said transparent cover plate member.

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